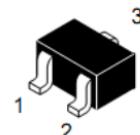


## WNM3018

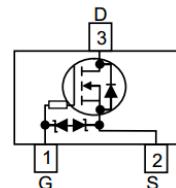
[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

### Small Signal N-Channel, 50V, 0.2A, MOSFET

<b>V<sub>DS</sub> (V)</b>	<b>Typical R<sub>Ds(on)</sub> (Ω)</b>
50	1.2@ V <sub>GS</sub> =10V
	1.4@ V <sub>GS</sub> =4.5V
	1.9@ V <sub>GS</sub> =2.5V
	5.4@ V <sub>GS</sub> =1.8V
ESD Rating: 2000V HBM	



SOT-323

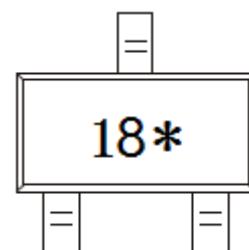


### Descriptions

The WNM3018 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R<sub>Ds(on)</sub> with low gate charge. This device is suitable for use in small signal switch. Standard Product WNM3018 is Pb-free and Halogen-free.

### Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- HBM ESD protection >2 kV
- Small package SOT-323



18 = Device Code  
\* = Month (A~Z)

### Marking

### Applications

- Driver: Relay, Solenoid, Lamps,Hammers etc.
- Power supply converters circuit
- Load/Power Switching for potable device

### Order information

Device	Package	Shipping
WNM3018-3/TR	SOT-323	3000/Reel&Tape

### Absolute Maximum ratings

Parameter	Symbol	10 S	Steady State	Unit
Drain-Source Voltage	V <sub>DS</sub>	50		V
Gate-Source Voltage	V <sub>GS</sub>	±20		
Continuous Drain Current <sup>a d</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	0.25	A
	T <sub>A</sub> =70°C		0.20	
Maximum Power Dissipation <sup>a d</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	0.37	W
	T <sub>A</sub> =70°C		0.24	
Continuous Drain Current <sup>b d</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	0.22	A
	T <sub>A</sub> =70°C		0.17	
Maximum Power Dissipation <sup>b d</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	0.28	W
	T <sub>A</sub> =70°C		0.18	
Pulsed Drain Current <sup>c</sup>	I <sub>DM</sub>		1.0	A
Operating Junction Temperature	T <sub>J</sub>		-55 to 150	°C
Lead Temperature	T <sub>L</sub>		260	°C
Storage Temperature Range	T <sub>stg</sub>		-55 to 150	°C

### Thermal resistance ratings

Parameter	Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>a</sup>	t ≤ 10 s	R <sub>θJA</sub>	285	335
	Steady State		340	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	t ≤ 10 s	R <sub>θJA</sub>	385	450
	Steady State		455	
Junction-to-Case Thermal Resistance	R <sub>θJC</sub>	260	300	

a Surface mounted on FR-4 Board using 1 square inch pad size, 1oz copper

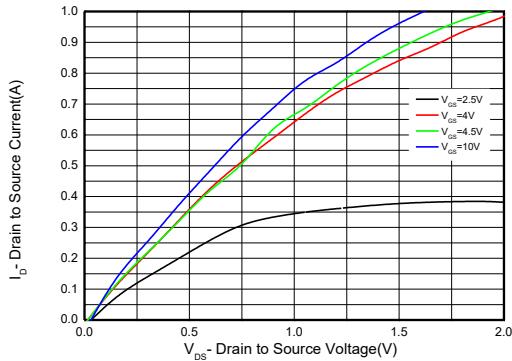
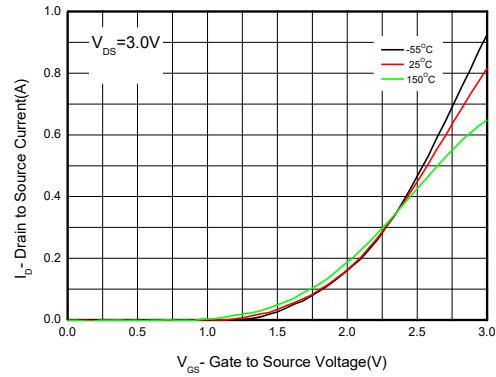
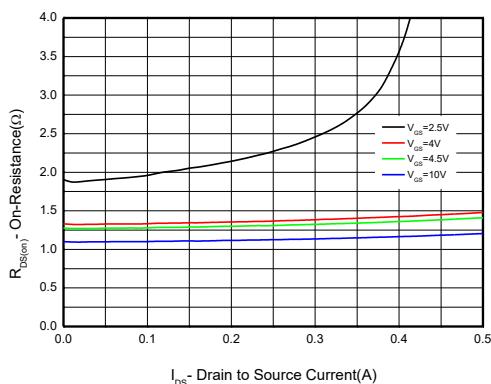
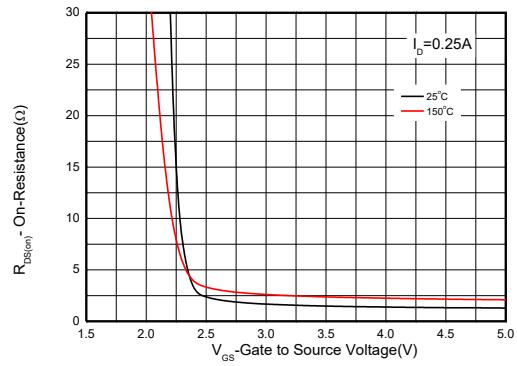
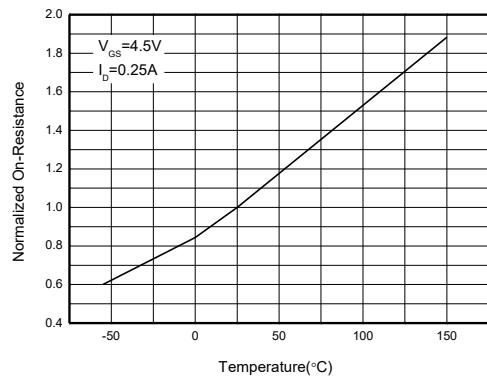
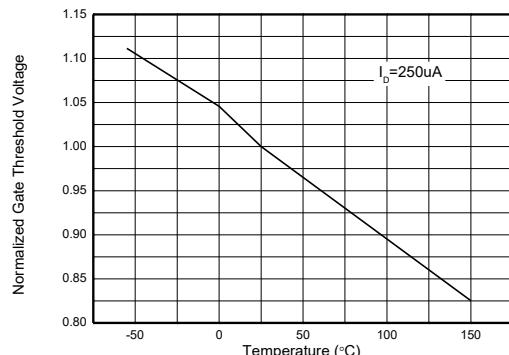
b Surface mounted on FR-4 board using minimum pad size, 1oz copper

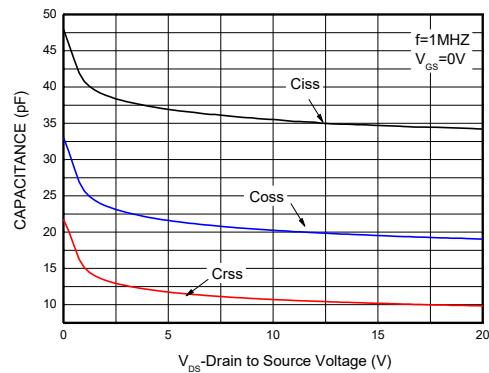
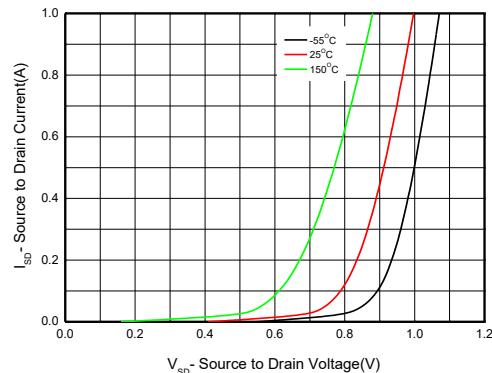
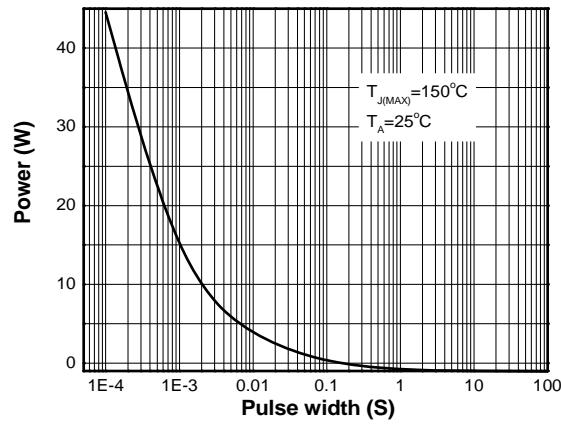
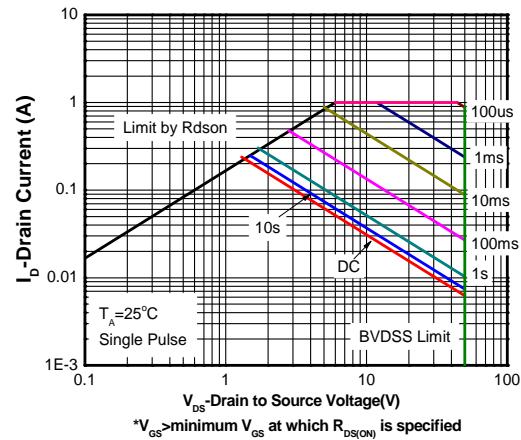
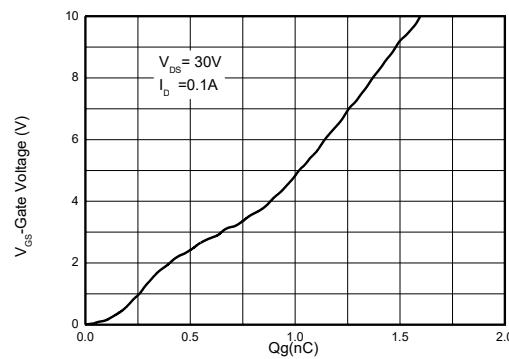
c Pulse width<380μs, Duty Cycle<2%

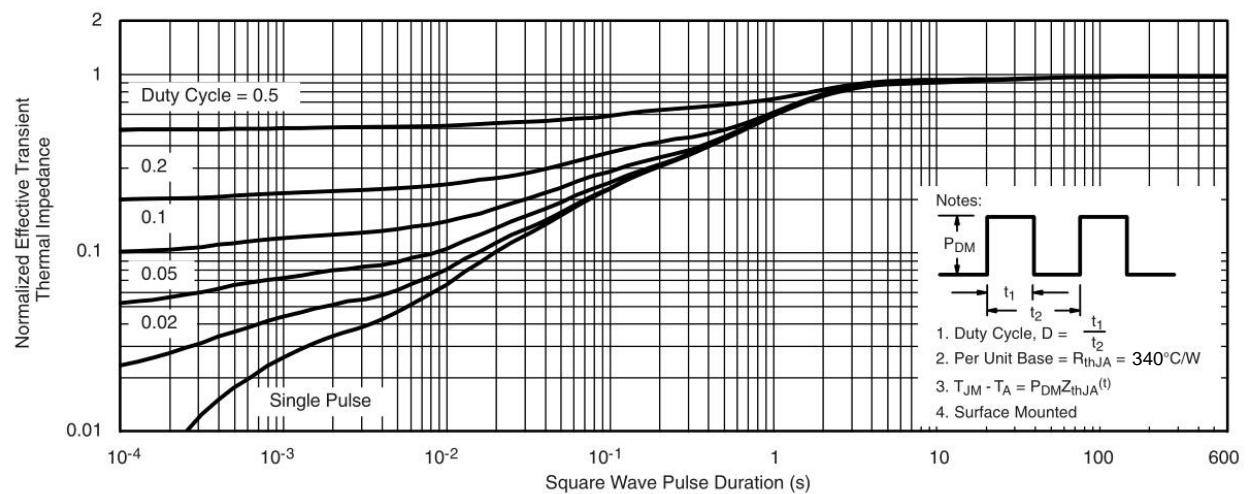
d Maximum junction temperature T<sub>J</sub>=150°C.

**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

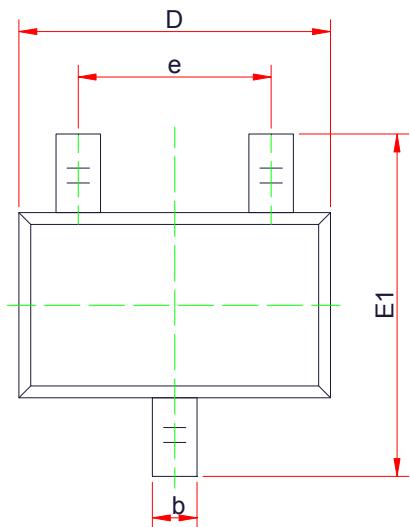
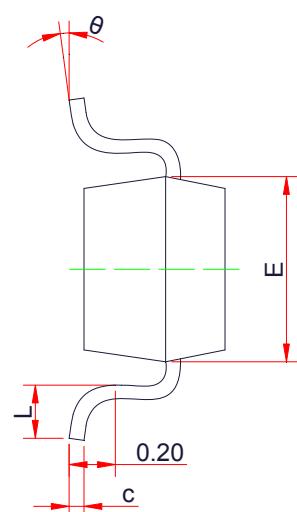
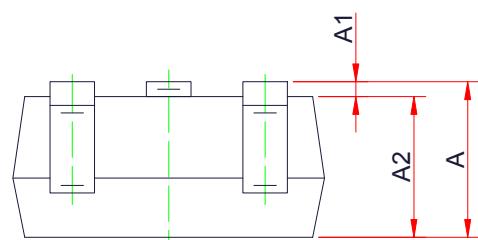
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250uA	50			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V			1	uA
Gate-to-source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20V			±5	uA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250uA	0.7	1.0	1.5	V
Drain-to-source On-resistance <sup>b, c</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.45A		1.2	3	Ω
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.25A		1.3	4	
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 0.01A		1.9	6	
		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 0.01A		5.4	15	
Forward Trans conductance	g <sub>fs</sub>	V <sub>DS</sub> = 15V, I <sub>D</sub> = 0.1A		0.5		S
<b>CAPACITANCES, CHARGES</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V,		36		pF
Output Capacitance	C <sub>OSS</sub>	F = 1.0 MHz,		22		
Reverse Transfer Capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 5 V		12		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 10 V, V <sub>DD</sub> = 30 V, I <sub>D</sub> = 0.1 A		1.6		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>			0.25		
Gate-to-Source Charge	Q <sub>GS</sub>			0.4		
Gate-to-Drain Charge	Q <sub>GD</sub>			0.45		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	td(ON)	V <sub>GS</sub> = 5 V, V <sub>DD</sub> = 5 V, R <sub>L</sub> =500 Ω, R <sub>G</sub> =10 Ω, I <sub>D</sub> = 10m A		8.6		ns
Rise Time	tr			4		
Turn-Off Delay Time	td(OFF)			23.8		
Fall Time	tf			14.2		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 0.25A		0.8	1.5	V

**Typical Characteristics (Ta=25°C, unless otherwise noted)**

**Output characteristics**

**Transfer characteristics**

**On-Resistance vs. Drain current**

**On-Resistance vs. Gate-to-Source voltage**

**On-Resistance vs. Junction temperature**

**Threshold voltage vs. Temperature**

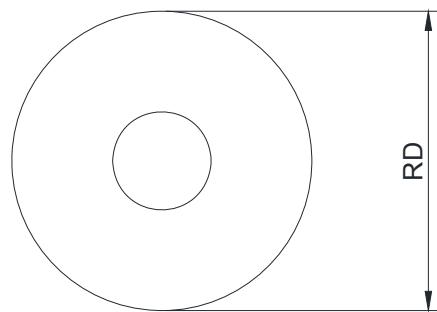
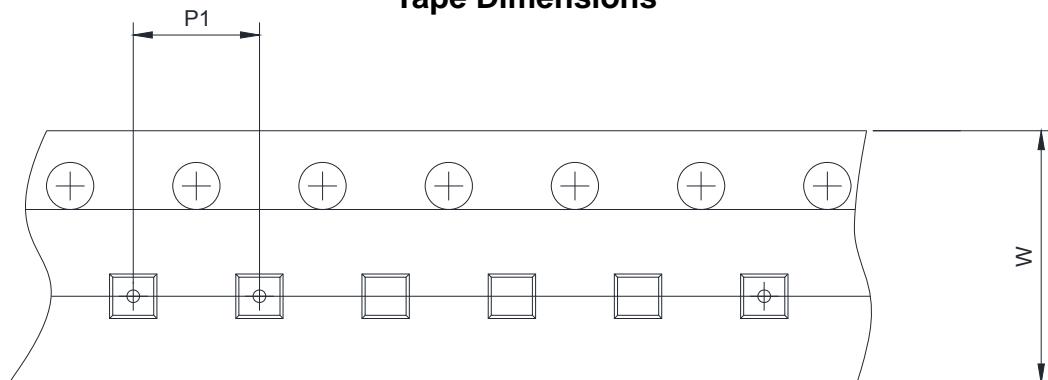
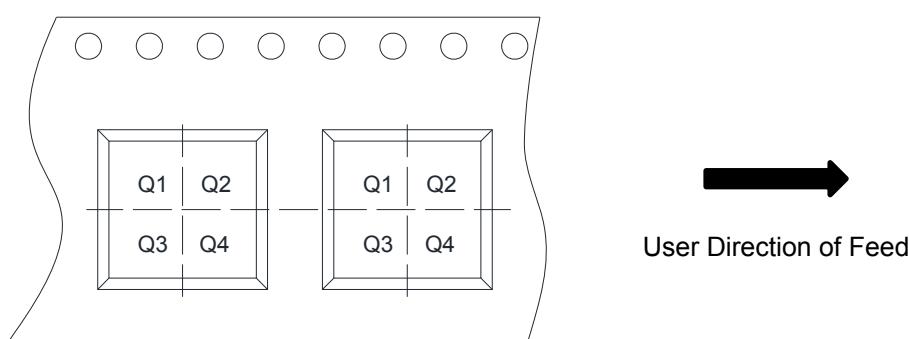

**Capacitance**

**Body diode forward voltage**

**Single pulse power**

**Safe operating power**

**Gate charge Characteristics**



**Transient thermal response (Junction-to-Ambient)**

**Package outline dimensions**
**SOT-323**

**TOP VIEW**

**SIDE VIEW**

**SIDE VIEW**

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.80	0.95	1.10
A1	0.00	-	0.10
A2	0.65	0.83	1.00
b	0.20	0.30	0.40
c	0.05	-	0.15
D	1.90	2.05	2.20
E	1.15	1.25	1.35
E1	2.00	2.23	2.45
e	1.20	1.30	1.40
L	0.20	0.33	0.46
$\theta$	0°	-	8°

**TAPE AND REEL INFORMATION**
**Reel Dimensions**

**Tape Dimensions**

**Quadrant Assignments For PIN1 Orientation In Tape**


<b>RD</b>	Reel Dimension	<input checked="" type="checkbox"/> 7inch <input type="checkbox"/> 13inch
<b>W</b>	Overall width of the carrier tape	<input checked="" type="checkbox"/> 8mm <input type="checkbox"/> 12mm <input type="checkbox"/> 16mm
<b>P1</b>	Pitch between successive cavity centers	<input type="checkbox"/> 2mm <input checked="" type="checkbox"/> 4mm <input type="checkbox"/> 8mm
<b>Pin1</b>	Pin1 Quadrant	<input type="checkbox"/> Q1 <input type="checkbox"/> Q2 <input checked="" type="checkbox"/> Q3 <input type="checkbox"/> Q4

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